EMI Filter with ESD Protection for SIM Card Applications

Product Description

The CM6310 is a 24-bump EMI filter with ESD protection device for data line application in a 0.5 mm pitch, 5 x 5 CSP form factor. It is fully compliant with IEC 61000-4-2. The CM6310 is RoHS II compliant.

Features

- 24-Bump, 2.60 mm X 2.60 mm Footprint Chip Scale Package
- These Devices are Pb-Free and are RoHS Compliant



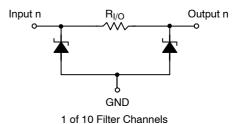
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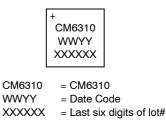


WLCSP24 CASE 567CJ

ELECTRICAL SCHEMATIC



MARKING DIAGRAM



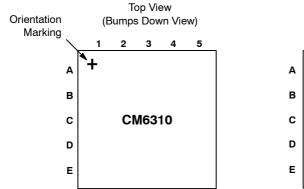
ORDERING INFORMATION

| Device | Package | Shipping [†] |
|--------|---------------------|-----------------------|
| CM6310 | CSP-24 (Pb-Free) | 5000/Tape & Reel |

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

CM6310

PACKAGE / PINOUT DIAGRAMS



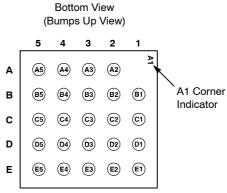


Table 1. PIN DESCRIPTIONS

| Pin | Description | Pin | Description | |
|-----|------------------|-----|-------------------|--|
| B1 | Channel 1 Input | D1 | Channel 1 Output | |
| C1 | Channel 2 Input | E1 | Channel 2 Output | |
| A2 | Channel 3 Input | D2 | Channel 3 Output | |
| C2 | Channel 4 Input | E2 | Channel 4 Output | |
| B2 | Channel 5 Input | D3 | Channel 5 Output | |
| C3 | Channel 6 Input | E3 | Channel 6 Output | |
| A5 | Channel 7 Input | D4 | Channel 7 Output | |
| C4 | Channel 8 Input | E4 | Channel 8 Output | |
| B5 | Channel 9 Input | D5 | Channel 9 Output | |
| C5 | Channel 10 Input | E5 | Channel 10 Output | |
| AЗ | GND | B3 | GND | |
| A4 | GND | B4 | GND | |

ELECTRICAL SPECIFICATIONS AND CONDITIONS

Table 2. PARAMETERS AND OPERATING CONDITIONS

| Parameter | Rating | Units |
|-----------------------------|-------------|-------|
| Storage Temperature Range | -55 to +150 | °C |
| Operating Temperature Range | -40 to +85 | °C |

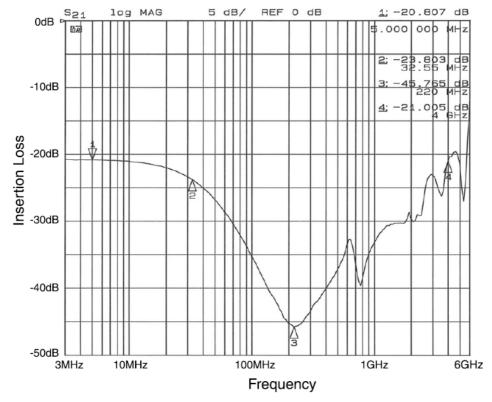
Table 3. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

| Symbol | Parameter | Conditions | Min | Тур | Max | Units |
|-------------------|--|---------------------------------|------------|------|------|-------|
| R _{I/O} | Resistance | | 900 | 1000 | 1100 | Ω |
| С | Capacitance per line | At 1 MHz, V _{IN} = 0 V | 80 | 100 | 120 | pF |
| V _{BR} | Breakdown voltage (Reverse) | I _R = 1 mA | 6 | 8 | 10 | V |
| I _{LEAK} | Leakage current at stand off voltage V_{RM} | V _{RM} = 3 V per line | | | 500 | nA |
| V _{ESD} | ESD Protection Peak Discharge Voltage a) Contact Discharge per IEC 61000-4-2 standard b) Air Discharge per IEC 61000-4-2 standard | (Note 2) | ±15 ±15 | | | kV |

1. All parameters specified at $T_A = 25^{\circ}C$ unless otherwise noted. 2. Standard IEC 61000–4–2 with $C_{Discharge} = 150 \text{ pF}$, $R_{Discharge} = 330 \Omega$.

CM6310

RF CHARACTERISTICS



T_A = 25°C, DC bias = 0 V, 50 Ω Environment Using Evaluation PCB

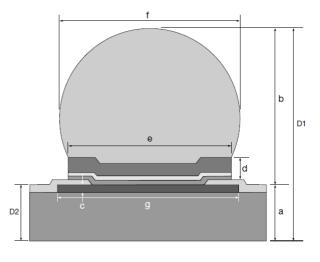


MECHANICAL SPECIFICATION

| Ref. | Parameter | Material | Dimension |
|------|---|--------------|-----------|
| а | Die Thickness | Silicon | 406 μm |
| b | Bump Standoff | | 240 μm |
| | UBM-(Ti/Cu) | Plated Cu | 5.0 μm |
| d | | Sputtered Cu | 0.4 μm |
| | | Sputtered Ti | 0.1 μm |
| е | UBM Wetting Area Diameter | | 280 μm |
| f | Solder Bump Diameter after Bump Reflow | | 320 μm |
| с | Metal Pad | AlSiCu | 1.5 μm |
| g | Metal Pad Diameter | | 324 μm |
| D2 | | | 0.406 mm |
| D1 | Finished Thickness | | 0.650 mm |

Table 4. VERTICAL STRUCTURE DIMENSIONS (nominal)

Vertical Structure Specification*



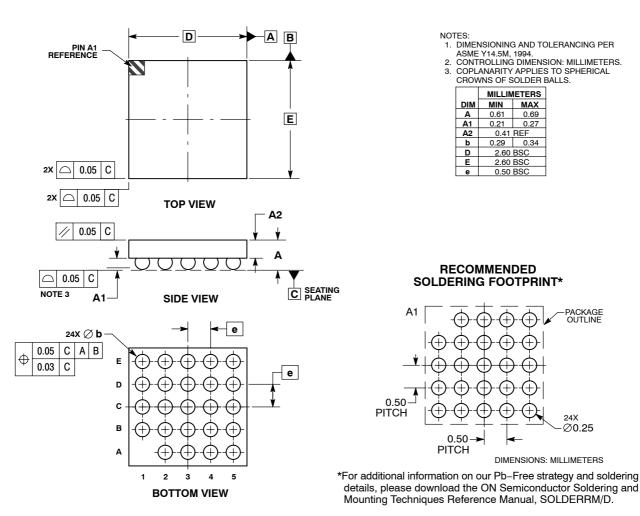




CM6310

PACKAGE DIMENSIONS

WLCSP24, 2.6x2.6 CASE 567CJ-01 ISSUE O



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